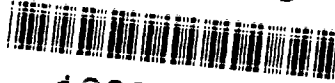


REC

10-27-1998



100861637

To the Honorable Commissioner of Patents and Trademarks 100861637 ed original documents or copy thereof

1. Name of conveying party(ies):

(a) Ho Tae Jin

(b) Hee Kook Choi **10.13.98**

Additional name(s) of conveying party(ies) attached?
 Yes No

2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Internal Address: _____

Street Address: 416, Maetan-dong, Paldal-ku, Suwon-city

City Kyungki-do State Republic of Korea ZIP _____

Additional name(s) & address(es) attached? Yes No

09/172715



3. Nature of Conveyance:

Assignment Merger

Security Agreement Change of Name

Other _____

Execution Date: a & b: October 2, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: October 2, 1998

A. Patent Application No.(s) - Not assigned

Title: Semiconductor Die Pickup Tool With Plural Contact Parts For Preventing Electrostatic Discharge

B. Patent No.(s)

N/A

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David T. Millers

Internal Address: SKJERVEN, MORRILL, MacPHERSON, FRANKLIN & FRIEL LLP

Street Address: 25 METRO DRIVE, SUITE 700

City SAN JOSE State CA ZIP 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

Authorized to be charged to Deposit Account 19-2386

Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David T. Millers 37,396 David Millers 10-13-98

Name of Person Signing Signature Date

Total number of pages comprising cover sheet: 2

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Ho Tae Jin

of

No.3-1404, Ssangyong Apt.
Ssangyong-dong, Cheonan-city
Chungcheongnam-do, Republic of Korea

Hee Kook Choi

of

No. 3-1001, Ssangyong Moran Apt.
Ssangyong-dong, Cheonan-city
Chungcheongnam-do, Republic of Korea

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-ku, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

Semiconductor Die Pickup Tool With Plural Contact Parts For Preventing Electrostatic Discharge

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 2nd day of October, 1998.

Ho Tae Jin

Ho Tae Jin

Executed this 2nd day of October, 1998.

Hee Kook Choi

Hee Kook Choi